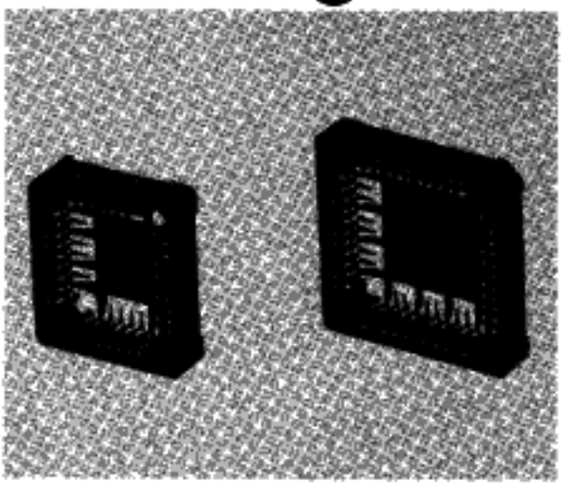
查询PLCC100GN供应商

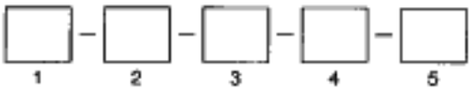


# PLASTIC LEADED CHIP CARRIER

*High Density Configuration Available



## ORDERING INFORMATION




**1. DESCRIPTION**
PLCC = Plastic Leaded Chip Carrier

**2. POSITION**
20, 28, 32, 44, 52, 68, 84, 100

**3. MOUNTING ANGLE**
TB = Through Board
SM = Surface Mount

**4. PLATING**
G = Gold over Nickel
T = Tin

**5. SPECIAL OPTIONS**
N = Thin wall for high density
(available in 32, 44, 68, 84)

**FEATURES:**

- Converts .050" chip centers to .100" board hole spacing
- Visual polarization for proper assembly orientation
- Closed bottom eliminates bridging and solder wicking
- Superior contact design allows proper seating and retention of JEDEC A, B and D chips

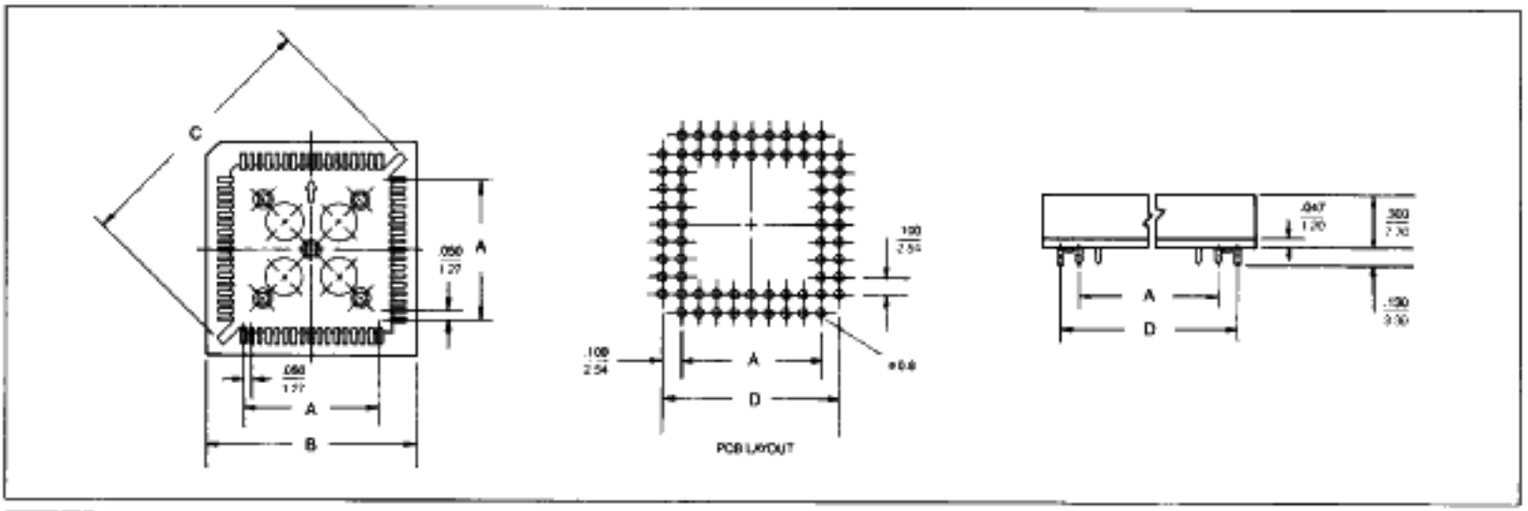
**PLCC SERIES SPECIFICATIONS:**

| MATERIALS: | |
|---|---|
| Contacts | Phosphor Bronze |
| Plating | Tin or gold over nickel |
| Insulator | PPS high temp. UL 94V-0 |

| ELECTRICAL: | |
|---|---|
| Current Rating | 1 Amp DC |
| Dielectric withstanding voltage: | 1000 VAC |
| Insulation Resistance | 1000 megohms min. |
| Contact Resistance | 5 milliohms typ. 20 max. |
| Operating Temperature | -65 to + 110 C |

## DIMENSIONAL DATA

All dimensions in (inches) and millimeters.




| No. of Contact Pos. | A | B | C | D |
|---|---|---|---|---|
| 20 | 5.08 (.200) | 15.58 (.613) | 18.30 (.720) | 10.16 (.400) |
| 28 | 7.62 (.300) | 18.12 (.713) | 21.86 (.860) | 12.70 (.500) |
| 32 | 7.62 (.300) | 17.60 (.692) | 23.00 (.905) | 12.60 (.496) |
| 44 | 12.70 (.500) | 24.50 (.960) | 30.04 (1.180) | 17.78 (700) |
| 52 | 15.24 (600) | 27.00 (1.060) | 32.64 (1.280) | 20.32 (.800) |
| 68 | 20.32 (.800) | 32.00 (1.260) | 39.70 (1.560) | 25.40 (1.000) |
| 84 | 25.40 (1.000) | 37.10 (1.460) | 46.90 (1.850) | 30.48 (1.200) |
| 100 | 31.75 (1.250) | 42.26 (1.664) | 54.10 (2.130) | 35.56 (1.400) |